Docket No.: FP04-326US 11-05-2004 ORM PTO-1595 (Modified) U.S. DEPARTMENT OF COMMERCE SHEET (Rev. 03-01) OMB No. 0651-0027 (exp.5/31/2002) Patent and Trademark Office P08A/REV03 Tab settings → → To the Director of the United States and Trademark Office: Please record the attached original documents or copy thereof. 1. Name of conveying party(ies): Name and address of receiving party(ies): Satoru Nishide Name Sumitomo Wiring Systems, Ltd. Address: 1-14, Nishisuehiro-cho 3. Nature of conveyance: Assignment ■ Merger City: Yokkaichi-City State/Prov.: Mie □ Security Agreement Change of Name ZIP: 510-8503 Country: Japan □ Other Execution Date: October 28, 2004 Additional name(s) & address(es) attached? X No Yes 4. Application number(s) or patent numbers(s): If this document is being filed together with a new application, the execution date of the application is: October 28, 2004 Patent Application No. Filing date B. Patent No.(s) Additional numbers attached?
Yes
No 5. Name and address of party to whom correspondence 6. Total number of applications and patents involved: concerning document should be mailed: Name: Gerald E. Hespos 7. Total fee (37 CFR 3.41):....\$ 40.00 30,066 Registration No. Enclosed - Any excess or insufficiency should be credited or debited to deposit account Address: 274 Madison Avenue - Suite 1703

11/04/2004 GTDW11 00000190 031030 10977690

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City: New York

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To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Gerald E. Hespos

Signaturé

October 29, 2004

2

Date

Name of Person Signing

Total number of pages including cover sheet, attachments, and document:

Atty. Ref.: FP04-326US

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned by the Assignee, Sumitomo Wiring Systems, Ltd., a corporation organized under the laws of Japan, located at 1-14, Nishisuehiro-cho, Yokkaichi-City, Mie, 510-8503 Japan, receipt whereof is hereby acknowledged, the undersigned by these presents hereby sells, assigns, transfers and sets over unto the said assignee the entire right, title and interest in and to the invention or improvement entitled "A DIVIDED CONNECTOR, A METHOD OF ASSEMBLING IT AND A METHOD OF CONNECTING IT WITH A MATING CONNECTOR", said invention being fully described and/or claimed in the application for Letters Patent of the United States of America, executed this date, in and for the United States and all foreign countries, the same to be held and enjoyed by said assignee, its successors, assigns or other legal representatives, to the full ends of the terms for which all Letters Patent therefor may be granted, as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

And Said Assignee Is Hereby Authorized to make application for and to receive Letters Patent for said invention in any of said countries at its election.

And By This Covenant The Undersigned will execute or procure any further necessary assurance of title to said invention and Letters Patent; and at any time, upon the request and at the expense of said assignee, will execute and deliver any and all papers that may be necessary or desirable to perfect the title to said invention or any Letters Patents which may be granted therefor in said Assignee, its successors, assigns or other legal representatives, and, upon the request and at the expense of said assignee, will execute any additional or divisional applications for patents for said invention, or any part or parts thereof, and for the reissue of any Letters Patents to be granted therefor, and will make all rightful oaths and do all lawful acts requisite for procuring the same or for aiding therein, without further compensation, but at the expense of said assignee, its successors, assigns or other legal representatives.

And The Commissioner Of Patents Is Hereby Authorized And Requested to issue any and all Letters Patent of the United States for said invention, to said assignee.

October 28. 2004

RECORDED: 10/29/2004

Satou Nishide

PATENT REEL: 015946 FRAME: 0030